



DuPont™ Pyralux® TK

Kapton® & Fluoropolymer Bond Ply

Flexible Circuit Materials

Product Description

DuPont™ Pyralux® TK Bond Ply features a layered dielectric, comprising a core ply of Kapton® covered on both sides with a low lamination temperature fluoropolymer. This bond ply can be used to encapsulate etched details for environmental protection and electrical insulation. Using bond ply can eliminate a layer of Kapton® dielectric and a layer of adhesive in low layer count multilayer constructions. Pyralux® TK can address your highest performance flex and rigid-flex applications where dielectric constant must fall below 3.0.

Key Features and Benefits

- Fluoropolymer film provides low-loss dielectric constant loss tangent
- Low moisture absorption for consistent performance
- Designed for use with Pyralux® TK Copper-Clad Laminates
- Certified to IPC-4203/5
- UL 94V-0, UL File E124294
- RoHS Compliant

Packaging

Pyralux® TK Bond Ply is supplied on 24 in. (610 mm) wide by 250 ft (76 m) long rolls, on nominal 3 in. (76 mm) cores. Narrower widths and alternative lengths, as well as sheets, are available by special order.

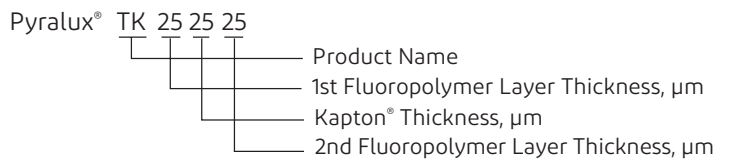
Storage

DuPont™ Pyralux® TK Bond Ply should be stored in original packaging at temperatures of 4 - 29 °C (40 - 85 °F) and below 70% relative humidity. The product should not be refrigerated or frozen and should be kept dry, clean, and well-protected. Subject to compliance with the foregoing handling and storage recommendations, DuPont's warranties shall remain in effect for the period provided in the DuPont Standard Conditions of Sale.

Table 1 - Standard Pyralux® TK Bond Ply Offerings

Product Code	Kapton® Thickness µm (mil)	Fluoropolymer Thickness µm (mil)
TK252525	25 (1.0)	25 (1.0)
TK255025	50 (2.0)	25 (1.0)
TK445044	50 (2.0)	44 (1.75)

Product Code Key



Processing

Lamination conditions for DuPont™ Pyralux® TK flexible circuit materials are typically in the following ranges:

Part Temperature:280 - 290 °C (535 - 554 °F)

Pressure:16.8 - 18.3 kg/cm² (240 - 260 psi)

Time:..... 1 hour, at temperature

Pyralux® TK Bond Ply processing guide available from your DuPont sales representative.

Safe Handling

Prior to handling, DuPont recommends referencing the Pyralux® Safe Handling Guide available at pyralux.dupont.com.

Quality and Traceability

DuPont™ Pyralux® TK Bond Ply is manufactured under a certified ISO9001:2015 Quality Management System facility. Complete material and manufacturing records, which include archive samples of finished product, are maintained by DuPont. Each manufactured lot is identified for reference traceability. The packaging label serves as the primary tracking mechanism in the event of customer inquiry and includes the product name, batch number, size, and quantity.

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Product Performance

Table 2 - DuPont™ Pyralux® TK Bond Ply Properties

Property	TK252525 Typical Value	Test Method
Dielectric Constant (Dk) 10 GHz, Normal	2.3	IPC-TM-650 2.5.5.5
10 GHz, In-plane	2.6	ASTM D2520
Loss Tangent (Df) 10 GHz	0.0015	ASTM D2520
Peel Strength Pyralux® TK Dielectric, N/mm (lb/in)	1.0 (6.0)	
As Received 36 µm Copper Foil, N/mm (lb/in)	0.87 (5.0)	
As Received 18 µm Shiny Copper, N/mm (lb/in)	0.50 (3.0)	IPC-TM-650 2.4.9
Solder Float, 288 °C for 10 s	Pass	IPC-TM-650 2.4.13
Moisture Absorption, %	0.3	IPC-TM-650 2.6.2
Dielectric Strength, V/µm	190	ASTM D149
Decomposition Temperature (2% / 5%), °C	494 / 514	DuPont Method, TMA

Data within this table are typical values for the listed product. Performance can vary depending on construction and processing.



pyralux.dupont.com

For more information on Pyralux® TK Bond Ply or other DuPont products, please visit our website.

The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. It may be subject to revision as new knowledge and experience becomes available. This information is not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of our products for your particular purposes. Since we cannot anticipate all variations in end-use and disposal conditions, DuPont makes no warranties and assumes no liability in connection with any use of this information. It is intended for use by persons having technical skill, at their own discretion and risk. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right.

CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

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EI-10131 (1/21)